

■ FEATURES

- Wide supply voltage range 4.5V \sim 18V
- Input range 500mV beyond the rails
- Unity-gain stable
- Rail-to-rail output swing
- High slew rate $3.2V/\mu s$
- **GBWP 3.5 MHz**
- 6 MHz -3dB Bandwidth
- Ultra-small Package TSSOP-14

APPLICATIONS

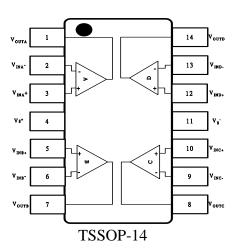
- TFT-LCD Reference Driver
- Touch-Screen Display
- Wireless LANs
- Personal Communication Devices
- Direct Access Arrangement
- Personal Digital Assistant (PDA)
- Active Filter
- Sampling ADC Amplifier
- ADC/DAC Buffer
- Electronic Notebook
- Office Automation

■ GENERAL DESCRIPTION

The EC5534 is a 100mA output current rail-to-rail quad channels operational amplifier with wide supply range from 4.5V to 18V while consumes only 1.1mA per channel. It provides 0.5V beyond the supply rails of common mode input range and capability of rail-to-rail output swing as well. This enables the amplifier to offer maximum dynamic range at any supply voltage among many applications. A 3.5MHz gain bandwidth product allows EC5534 to perform more stable than other devices in Internet applications.

With features of $3.2V/\mu$ s high slew rate and $1.3 \,\mu$ s of fast settling time, as well as 100 mA(sink and source) of high output driving capability, the EC5534 is ideal for the requirements of flat panel Thin Film Transistor Liquid Crystal Displays (TFT-LCD) panel application. reference buffers Due insensitive to power supply variation, EC5534 offers flexibility of use in multitude of applications such as battery power, portable devices and anywhere low power consumption concerned. With standard operational amplifier pin assignment, the EC5534 is offered in space saving 14-Pin TSSOP package and specified over the -40°C to +85°C temperature range.

■ PIN ASSIGNMENT



Rev 0.1

EC5534

■ ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

Values beyond absolute maximum ratings may cause permanent damage to the device. These are stress ratings only; functional device operation is not implied. Exposure to AMR conditions for extended periods may affect device reliability.

Supply Voltage between V_{S+} and V_{S-} +20V Storage Temperature -65°C to +150°C Input Voltage V_{S-} -0.5V, V_{S+} +0.5V Operating Temperature -40°C to +85°C Maximum Continuous Output Current 100mA Lead Temperature 260°C Maximum Die Temperature +125°C ESD Voltage 2kV

Important Note:

All parameters having Min/Max specifications are guaranteed. Typical values are for information purposes only. Unless otherwise noted, all tests are at the specified temperature and are pulsed tests, therefore: TJ = TC = TA

ELECTRICAL CHARACTERISTICS

 V_{S+} = +5V, V_{S-} = -5V, R_L = 10k Ω and C_L = 10pF to 0V, T_A = 25°C unless otherwise specified.

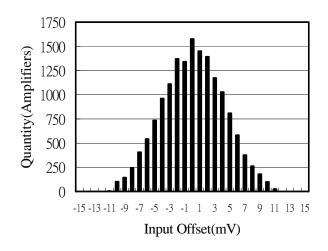
Parameter	Description	Condition	Min	Тур	Max	Units	
Input Characte	eristics						
V_{OS}	Input Offset Voltage	$V_{CM} = 0V$		2	12	mV	
TCV_{OS}	Average Offset Voltage Drift	[1]		5		μV/°C	
I_{B}	Input Bias Current	$V_{CM} = 0V$		2	50	nA	
$R_{\rm IN}$	Input Impedance			1		GΩ	
C_{IN}	Input Capacitance			1.35		pF	
CMIR	Common-Mode Input Range		-0.5		+5.5	V	
CMRR	Common-Mode Rejection Ratio	for V_{IN} from -0.5V to 5.5V	50	70		dB	
A_{VOL}	Open-Loop Gain	$0.5V \le V_{OUT} \le 4.5V$	75	100		dB	
Output Characteristics							
V_{OL}	Output Swing Low	$I_L = -5 \text{mA}$		-4.92	-4.85	mV	
$V_{ m OH}$	Output Swing High	$I_L=5mA$	4.85	4.92		V	
${ m I}_{ m SC}$	Short Circuit Current			±300		mA	
$ m I_{OUT}$	Output Current			±100		mA	
Power Supply Performance							
PSRR	Power Supply Rejection Ratio	V _S is moved from ±2.25V to ±7.75V	60	80		dB	
I_S	Supply Current (Per Amplifier)	No Load		1.5	1.7	mA	
Dynamic Perfor	rmance						
SR	Slew Rate [2]	$-4.0V \le V_{OUT} \le 4.0V$, 20% to 80%		3.2		V/µs	
t_S	Settling to $+0.1\%$ (AV = $+1$)	$(AV = +1)$, $V_0 = 2V$ Step		1.3		μs	
BW	-3dB Bandwidth	$R_L = 10k\Omega, C_L = 10pF$		6		MHz	
GBWP	Gain-Bandwidth Product	$R_L = 10k\Omega$, $CL=10pF$	3.5			MHz	
PM	Phase Margin	$RL = 10k\Omega$, $CL = 10 pF$		60		Degrees	
CS	Channel Separation	f = 1 MHz		75		dB	

^{1.} Measured over operating temperature range

PAGE 3 of 9 Rev 0.1

^{2.} Slew rate is measured on rising and falling edges

■ TYPICAL PERFORMANCE CURVES



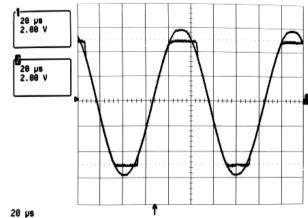
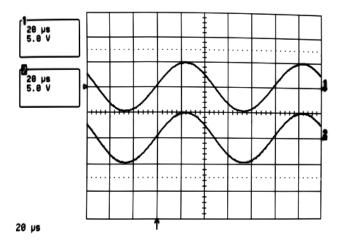


Figure (a) Input Offset Voltage Distribution

Figure (b) Input beyond the rails



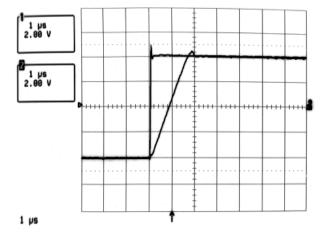
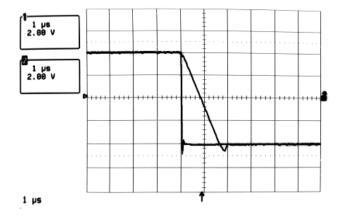


Figure (c) Rail to Rail Capability

Figure (d) Large Signal Transient Response



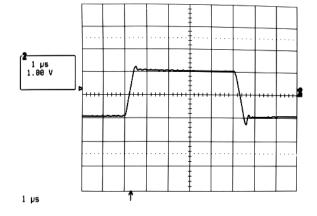


Figure (e) Large Signal Transient Response

Figure (f) Small Signal Transient Response

PAGE 3 of 9 Rev 0.1

■ TYPICAL PERFORMANCE CURVES

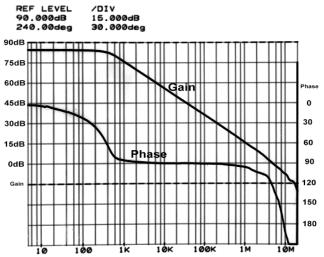


Figure (g) Open Loop Gain & Phase vs. Frequency

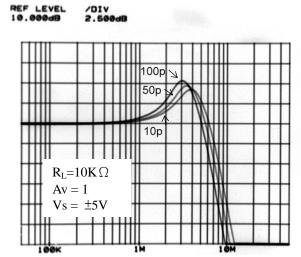


Figure (h) Frequency Response for Various C_L

REF LEVEL /DIV 10.000dB 2.500dB

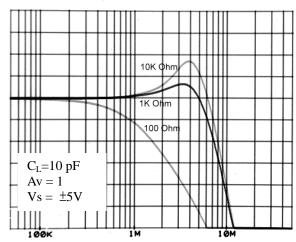


Figure (h) Frequency Response for Various R_L

PAGE 4 of 9 Rev 0.1

APPLICATIONS INFORMATION

Product Description

The EC5534 rail-to-rail quad channels amplifier is built on an advanced high voltage CMOS process. It's beyond rails input capability and full swing of output range made itself an ideal amplifier for use in a wide range of general-purpose applications. The features of $3.2 \text{V}/\mu\text{S}$ high slew rate, fast settling time, 3.5 MHz of GBWP as well as high output driving capability have proven the EC5534 a good voltage reference buffer for TFT-LCD for applications. High phase margin make the EC5534 ideal for Connected in voltage follower mode for high drive applications

Supply Voltage, Input Range and Output Swing

The EC5534 can be operated with a single nominal wide supply voltage ranging from 4.5V to 18V with stable performance over operating temperatures of -40 $^{\circ}$ C to +85 $^{\circ}$ C.

With 500mV greater than rail-to-rail input common mode voltage range and 70dB of Common Mode Rejection Ratio, the EC5534 allows a wide range sensing among many applications without having any concerns over exceeding the range and no compromise in accuracy. The output swings of the EC5534 typically extend to within 80mV of positive and negative supply rails with load currents of 5mA. The output voltage swing can be even closer to the supply rails by merely decreasing the load current. Figure 1 shows the input and output waveforms for the device in the unity-gain configuration. The amplifier is operated under $\pm 5 V$ supply with a $10 k\Omega$ load connected to GND. The input is a 10 Vp-p sinusoid. An approximately 9.985 Vp-p of output voltage swing can be easily achieved.

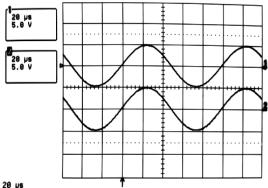


Figure 1. Operation with Rail-to-Rail Input and Output

Output Short Circuit Current Limit

A +/-300mA short circuit current will be limited by the EC5534 if the output is directly shorted to the positive or the negative supply. For an indefinitely output short circuit, the power dissipation could easily increase such

that the device may be damaged. The internal metal interconnections are well designed to prevent the output continuous current from exceeding +/-100 mA such that the maximum reliability can be well maintained.

Output Phase Reversal

The EC5534 is designed to prevent its output from being phase reversal as long as the input voltage is limited from $V_{S^{\perp}}-0.5V$ to $V_{S^{\perp}}+0.5V$. Figure 2 shows a photo of the device output with its input voltage driven beyond the supply rails. Although the phase of the device's output will not be reversed, the input's over-voltage should be avoided. An improper input voltage exceeds supply range by more than 0.6V may result in an over stress damage.

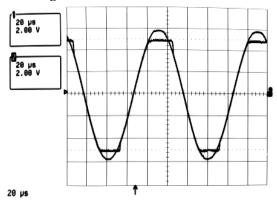


Figure 2. Operation with Beyond-the Rails Input

Power Dissipation

The EC5534 is designed for maximum output current capability. Even though momentary output shorted to ground causes little damage to the device.

For the high drive amplifier EC5534, it is possible to exceed the 'absolute-maximum junction temperature' under certain load current conditions. Therefore, it is important to calculate the maximum junction temperature for the application to determine if load conditions need to be modified for the amplifier to remain in the safe operating area. The maximum power dissipation allowed in a package is determined according to:

$$P_{\text{Dmax}} = \frac{T_{\text{Jmax}} - T_{\text{Amax}}}{\Theta_{\text{JA}}}$$

Where:

 T_{Jmax} = Maximum Junction Temperature

 T_{Amax} = Maximum Ambient Temperature

 Θ_{JA} = Thermal Resistance of the Package

 P_{Dmax} = Maximum Power Dissipation in the Package.



The maximum power dissipation actually produced by an IC is the total quiescent supply current times the total power supply voltage, plus the power in the IC due to the loads, or:

$$P_{Dmax} = \sum_{i} [V_{S} * I_{Smax} + (V_{S+} - V_{O}) * I_{L}]$$

When sourcing, and

$$P_{Dmax} = \sum_{i} [\mathbf{V}_{S} * \mathbf{I}_{Smax} + (\mathbf{V}_{O} - \mathbf{V}_{S} -) * \mathbf{I}_{L}]$$

When sinking.

Where:

 $\mathbf{i} = 1 \text{ to } 4$

 V_S = Total Supply Voltage

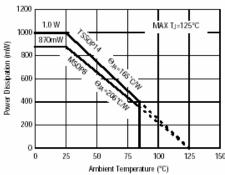
 I_{Smax} = Maximum Supply Current Per Amplifier

 V_0 = Maximum Output Voltage of the Application

I_L= Load current

$$\mathbf{R_L}$$
= Load Resistance = $(\mathbf{V_{S+}} - \mathbf{V_O})/\mathbf{I_L} = (\mathbf{V_O} - \mathbf{V_{S-}})/\mathbf{I_L}$

A calculation for R_L to prevent device from overheat can be easily solved by setting the two P_{Dmax} equations equal to each other. Figure 3 and Figure 4 show the relationship between package power dissipation and ambient temperature under the JEDEC JESD 51-7 high effective thermal conductivity test board and SEMI G42-88 single layer test board respectively. From these charts, conditions of the device overheat then can be easily found. The maximum safe power dissipation can be found graphically, based on the package type and the ambient temperature. By using the previous equation, it is a simple matter to see if P_{DMAX} exceeds the device's power de-rating curves. To ensure proper operation, it is important to observe the recommended de-rating curves shown in Figure 3 and Figure 4.



JEDEC JESD 51-7 High Effective Thermal Conductivity Test Board

Figure 3. Package Power Dissipation vs.
Ambient Temperature

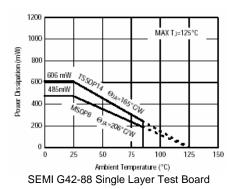


Figure 4. Package Power Dissipation vs.
Ambient Temperature

Driving Capacitive Loads

The EC5534 is designed to drive a wide range of capacitive loads. In addition, the output current handling capability of the device allows for good slewing characteristics even with large capacitive loads. The combination of these features make the EC5534 ideally for applications such as TFT LCD panel buffers, ADC input amplifiers, etc.

As load capacitance increases, however, the -3dB bandwidth of the device will decrease and the peaking increase. The amplifiers drive 10pF loads in parallel with 10 k Ω with just 1.5dB of peaking, and 100pF with 6.4dB of peaking. If less peaking is desired in these applications, a small series resistor (usually between 5 Ω and 50 Ω) can be placed in series with the output. However, this will obviously reduce the gain slightly. Another method of reducing peaking is to add a "snubber" circuit at the output. A snubber is a shunt load consisting of a resistor in series with a capacitor. Values of 150 Ω and 10nF are typical. The advantage of a snubber is that it improves the settling and overshooting performance while does not draw any DC load current or reduce the gain.

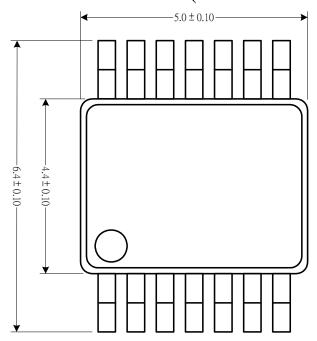
Power Supply Bypassing and Printed Circuit Board Layout

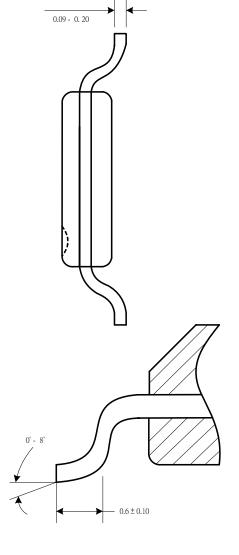
With high phase margin, the EC5534 performs stable gain at high frequency. Like any high-frequency device, good layout of the printed circuit board usually comes with optimum performance. Ground plane construction is highly recommended, lead lengths should be as short as possible and the power supply pins must be well bypassed to reduce the risk of oscillation. For normal single supply operation, where the V_{S^-} pin is connected to ground, a 0.1 μF ceramic capacitor should be placed from V_{S^+} pin to V_{S^-} pin as a bypassing capacitor. A 4.7 μF tantalum capacitor should then be connected in parallel, placed in the region of the amplifier. One 4.7 μF capacitor may be used for multiple devices. This same capacitor combination should be placed at each supply pin to ground if split supplies are to be used.

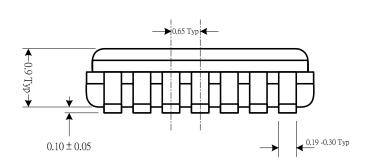


■ **OUTLINE DIMENSIONS** (Dimensions shown in millimeters)

TSSOP (Thin-Shrink Small Outline Package)



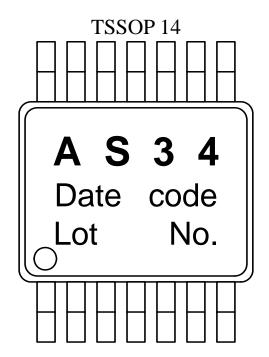




PAGE 7

of 9

■ PACKAGE MARKING INDICATION



■ ORDERING INFORMATION

PART NUMBER	TOP MARK	PACKAGE
EC5534I	AS34	14-Pin TSSOP
EC5534I-F	AS34-F	Leadfree 14-pin TSSOP
EC5534I-G	AS34-G	Green mode TSSOP-14

PAGE 8 of 9 Rev 0.1



General Disclaimer:

- 1. Product information and specifications furnished by E-CMOS in this data sheets are in effect as of the publication date shown and are believed to be accurate and reliable. However, no responsibility is assumed by E-CMOS for the use of any information shown herein, nor for any patent or other rights infringement.
- 2. No license is granted by implication or otherwise under any patent or industrial properties owned by E-CMOS or any third party through this document.
- 3. The information herein is subject to change at any time without notice.
- 4. Neither reproduction nor duplication of this document, in any form, the whole or part is allowed without the prior written approval from E-CMOS.
- 5. Products of E-CMOS Corp., unless otherwise specified, are not authorized for use as critical components of any device or equipment in applications that demand extremely high reliability or where its failure or malfunction may directly threaten human life or cause risk of bodily injury, such as aerospace, aircraft, vehicles, nuclear power, radiation resistant system, transportation, disaster prevention equipment, gas related equipment, physical exercise equipment, safety equipment and medical equipment for life support, etc.
- 6. Although E-CMOS makes every attempt to ensure that its products are of high quality and reliability, thorough consideration of safety design and operating within the ranges guaranteed are strongly recommended to prevent any accident and damage that may ensue. E-CMOS bares no responsibility for failure or damage when abused or used beyond the guaranteed ranges.
- 7. Products applied to life support devices and systems are strongly requested to contact E-CMOS Corporation headquarter for the written approval to establish suitable terms & conditions. E-CMOS' warranty is limited to replacement of defective components. Any personal injury or death or any other consequential damages of property are not covered.

Copyright © 2002 by E-CMOS Corporation.

E-CMOS CORPORATION IC DATASHEET

ADDRESS: NO.1, CREATION RD. 2ND, SCIENCE-BASED INDUSTRIAL PARK,

HSIN-CHU 300, TAIWAN, R.O.C.

WEBSITE: http://www.ecmos.com.tw

E-MAIL: mailto:sales@ecmos.com.tw

TEL: 886-3-5785888 FAX: 886-3-5783630